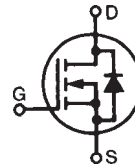


PolarHV™ Power MOSFET

IXTP 1R4N60P
IXTU 1R4N60P
IXTY 1R4N60P

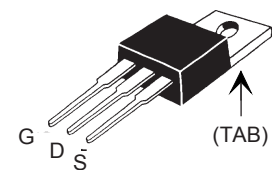
V_{DSS} = 600 V
I_{D25} = 1.4 A
R_{DS(on)} ≤ 9.0 Ω

N-Channel Enhancement Mode
Avalanche Rated

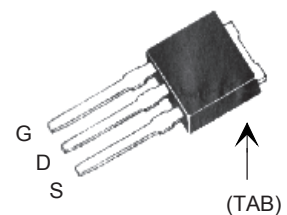


Symbol	Test Conditions	Maximum Ratings	
V _{DSS}	T _J = 25° C to 175° C	600	V
V _{DGR}	T _J = 25° C to 175° C; R _{GS} = 1 MΩ	600	V
V _{GS}	Continuous	±30	V
V _{GSM}	Transient	±40	V
I _{D25}	T _C = 25° C	1.4	A
I _{DM}	T _C = 25° C, pulse width limited by T _{JM}	2.1	A
I _{AR}	T _C = 25° C	1.4	A
E _{AR}	T _C = 25° C	5	mJ
E _{AS}	T _C = 25° C	75	mJ
dv/dt	I _S ≤ I _{DM} , di/dt ≤ 100 A/μs, V _{DD} ≤ V _{DSS} , T _J ≤ 150° C, R _G = 20 Ω	10	V/ns
P _D	T _C = 25° C	50	W
T _J		-55 ... +150	°C
T _{JM}		150	°C
T _{stg}		-55 ... +150	°C
T _L	1.6 mm (0.062) from case for 10 s	300	°C
T _{SOLD}	Plastic body for 10 s	260	°C
Weight	TO-220	4.0	g
	TO-252	0.35	g
	TO-251	0.4	g

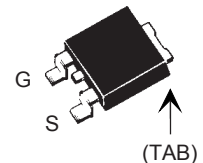
TO-220 (IXTP)



TO-251 (IXTU)



TO-252 (IXTY)



G = Gate D = Drain
S = Source TAB = Drain

Symbol	Test Conditions (T _J = 25° C, unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
BV _{DSS}	V _{GS} = 0 V, I _D = 25 μA	600		V
V _{GS(th)}	V _{DS} = V _{GS} , I _D = 25 μA	3.0		5.5 V
I _{GSS}	V _{GS} = ±30 V _{DC} , V _{DS} = 0			±50 nA
I _{DSS}	V _{DS} = V _{DSS} , V _{GS} = 0 V, T _J = 125° C			1 μA 20 μA
R _{DS(on)}	V _{GS} = 10 V, I _D = 0.5 I _{D25} Pulse test, t ≤ 300 μs, duty cycle d ≤ 2 %			9.0 Ω

Features

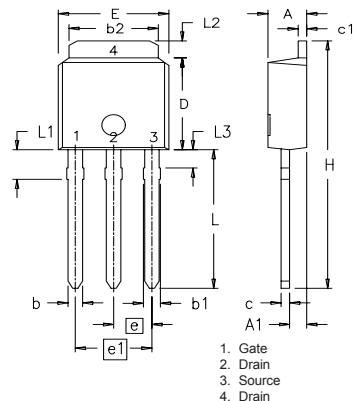
- † International standard packages
- † Unclamped Inductive Switching (UIS) rated
- † Low package inductance
- easy to drive and to protect

Advantages

- † Easy to mount
- † Space savings
- † High power density

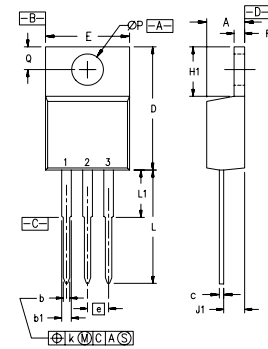
Symbol	Test Conditions	Characteristic Values		
		$(T_J = 25^\circ\text{C}, \text{ unless otherwise specified})$		
		Min.	Typ.	Max.
g_{fs}	$V_{DS} = 20\text{ V}; I_D = 0.5 I_{D25}, \text{ pulse test}$	0.7	1.1	S
C_{iss}	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$		140	pF
C_{oss}			17	pF
C_{rss}			2.4	pF
$t_{d(on)}$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 V_{DSS}, I_D = 0.5 I_{D25}$ $R_G = 50\ \Omega \text{ (External)}$		10	ns
t_r			16	ns
$t_{d(off)}$			25	ns
t_f			16	ns
$Q_{g(on)}$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 V_{DSS}, I_D = 0.5 I_{D25}$		5.2	nC
Q_{gs}			1.34	nC
Q_{gd}			5.2	nC
R_{thJC}				2.5°C/W
R_{thCS}	(TO-220)		0.25	$^\circ\text{C/W}$
R_{thCS}	(TO-251)		1.0	$^\circ\text{C/W}$

Source-Drain Diode		Characteristic Values		
		$(T_J = 25^\circ\text{C}, \text{ unless otherwise specified})$		
Symbol	Test Conditions	Min.	Typ.	Max.
I_S	$V_{GS} = 0\text{ V}$			1.4 A
I_{SM}	Repetitive			4 A
V_{SD}	$I_F = I_S, V_{GS} = 0\text{ V},$ Pulse test, $t \leq 300\ \mu\text{s}, \text{ duty cycle } d \leq 2\%$			1.5 V
t_{rr}	$I_F = 1.5\text{ A}, -di/dt = 100\text{ A}/\mu\text{s}$ $V_R = 100\text{ V}, V_{GS} = 0\text{ V}$		500	ns

TO-251 (IXTU) Outline


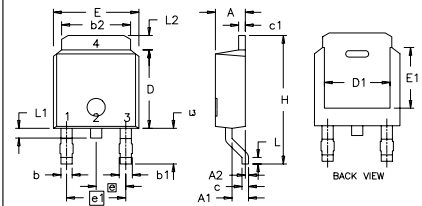
Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	2.19	2.38	.086	.094
A1	0.89	1.14	0.35	.045
b	0.64	0.89	.025	.035
b1	0.76	1.14	.030	.045
b2	5.21	5.46	.205	.215
c	0.46	0.58	.018	.023
c1	0.46	0.58	.018	.023
D	5.97	6.22	.235	.245
E	6.35	6.73	.250	.265
e	2.28	BSC	.090	BSC
e1	4.57	BSC	.180	BSC
H	17.02	17.78	.670	.700
L	8.89	9.65	.350	.380
L1	1.91	2.28	.075	.090
L2	0.89	1.27	.035	.050

1. Gate
2. Drain
3. Source
4. Drain

TO-220 (IXTP) Outline


- Pins: 1 - Gate 2,4 - Drain
3 - Source

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.170	.190	4.32	4.83
b	.025	.040	0.64	1.02
b1	.045	.065	1.15	1.65
c	.014	.022	0.35	0.56
D	.580	.630	14.73	16.00
E	.390	.420	9.91	10.66
e	.100	BSC	2.54	BSC
F	.045	.055	1.14	1.40
H1	.230	.270	5.85	6.85
J1	.090	.110	2.29	2.79
k	0	.015	0	0.38
L	.500	.550	12.70	13.97
L1	.110	.230	2.79	5.84
ØP	.139	.161	3.53	4.08
Q	.100	.125	2.54	3.18

TO-252 AA (IXTY) Outline


Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	2.19	2.38	0.086	0.094
A1	0.89	1.14	0.035	0.045
A2	0	0.13	0	0.005
b	0.64	0.89	0.025	0.035
b1	0.76	1.14	0.030	0.045
b2	5.21	5.46	0.205	0.215
c	0.46	0.58	0.018	0.023
c1	0.46	0.58	0.018	0.023
D	5.97	6.22	0.235	0.245
D1	4.32	5.21	0.170	0.205
E	6.35	6.73	0.250	0.265
E1	4.32	5.21	0.170	0.205
e	2.28	BSC	0.090	BSC
e1	4.57	BSC	0.180	BSC
H	9.40	10.42	0.370	0.410
L	0.51	1.02	0.020	0.040
L1	0.64	1.02	0.025	0.040
L2	0.89	1.27	0.035	0.050
L3	2.54	2.92	0.100	0.115

IXYS reserves the right to change limits, test conditions, and dimensions.

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one or more of the following U.S. patents: 4,850,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405B2 6,759,692
4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2

Fig. 1. Output Characteristics
@ 25°C

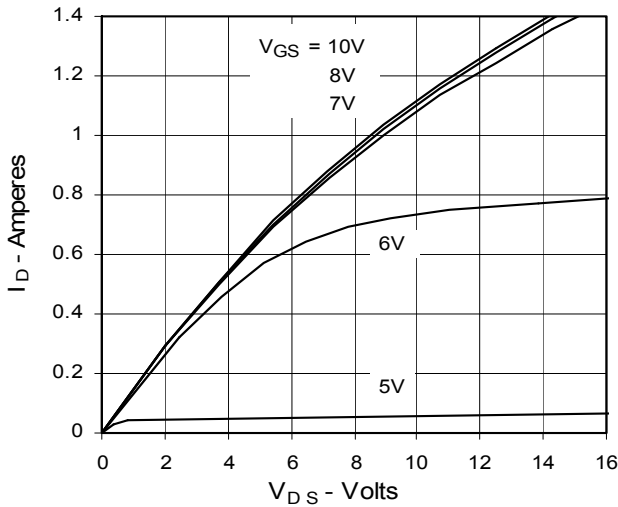


Fig. 2. Extended Output Characteristics
@ 25°C

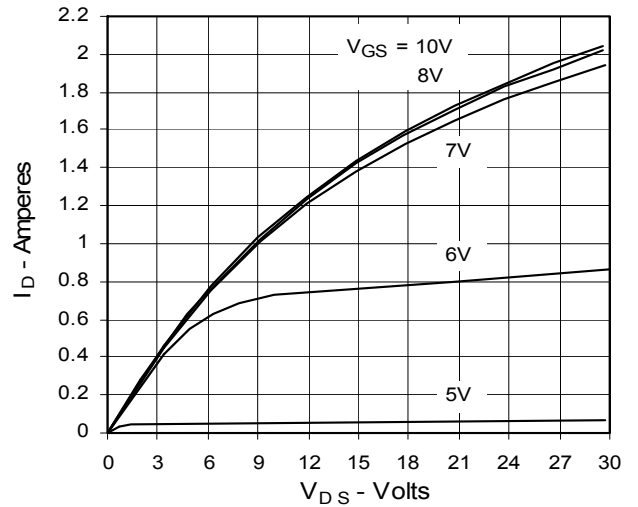


Fig. 3. Output Characteristics
@ 125°C

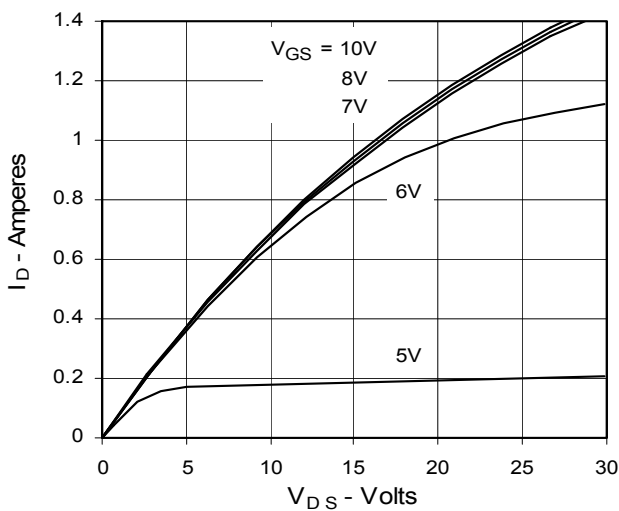


Fig. 4. $R_{DS(on)}$ Normalized to 0.5 I_{D25} Value vs. Junction Temperature

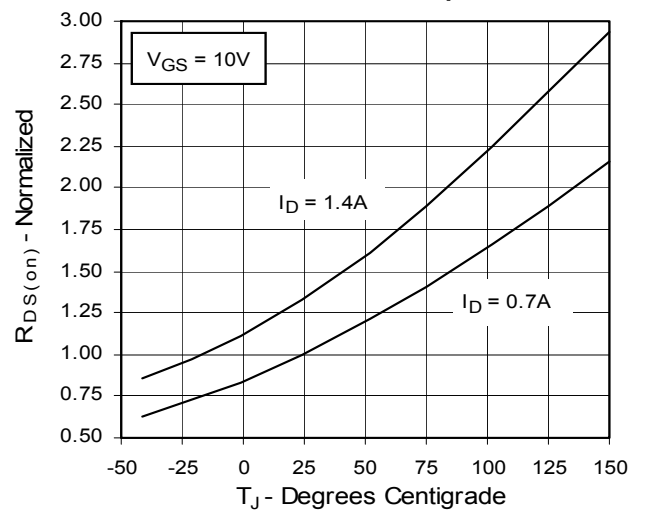


Fig. 5. $R_{DS(on)}$ Normalized to 0.5 I_{D25} Value vs. I_D

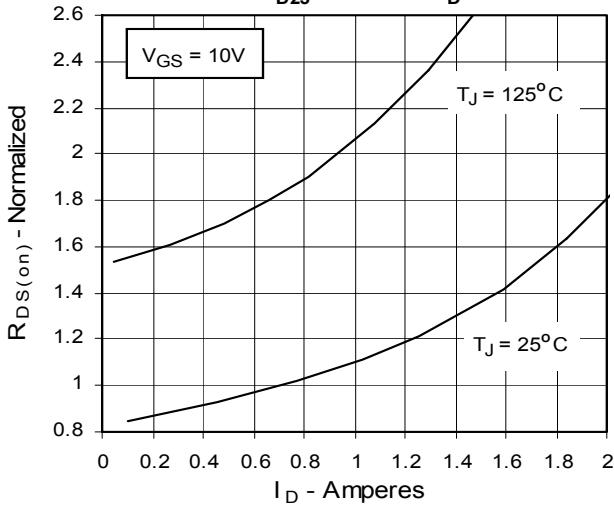


Fig. 6. Drain Current vs. Case Temperature

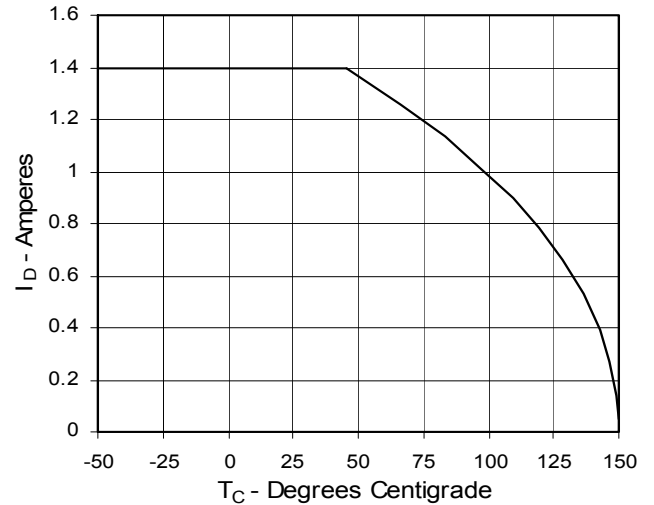


Fig. 7. Input Admittance

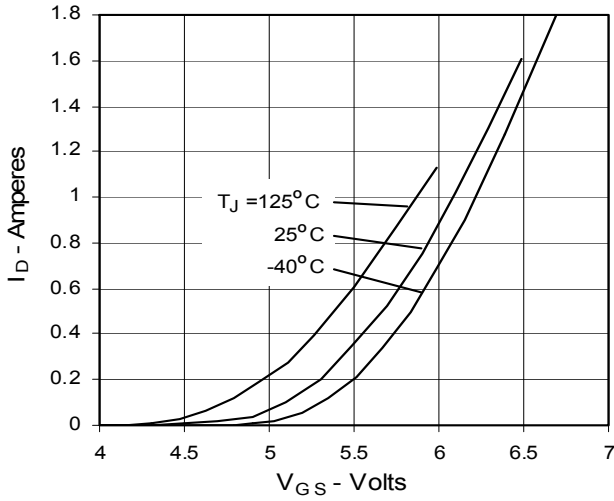


Fig. 8. Transconductance

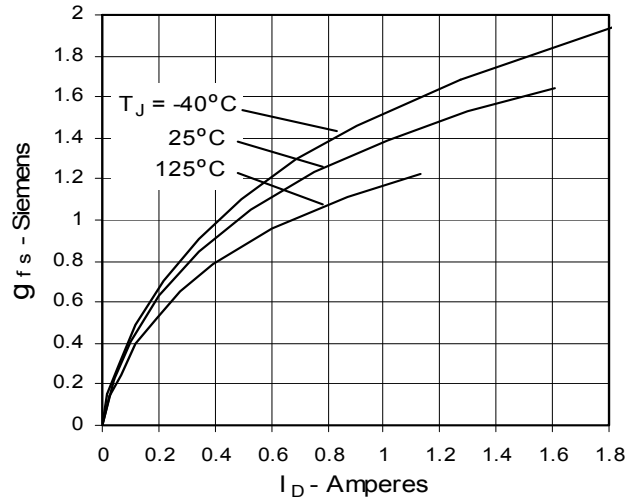


Fig. 9. Source Current vs. Source-To-Drain Voltage

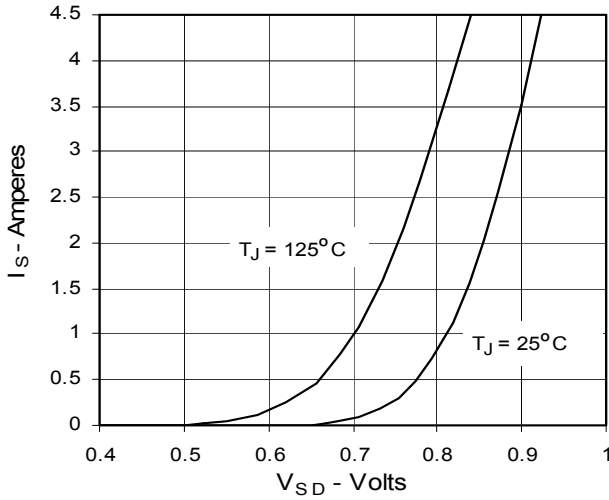


Fig. 10. Gate Charge

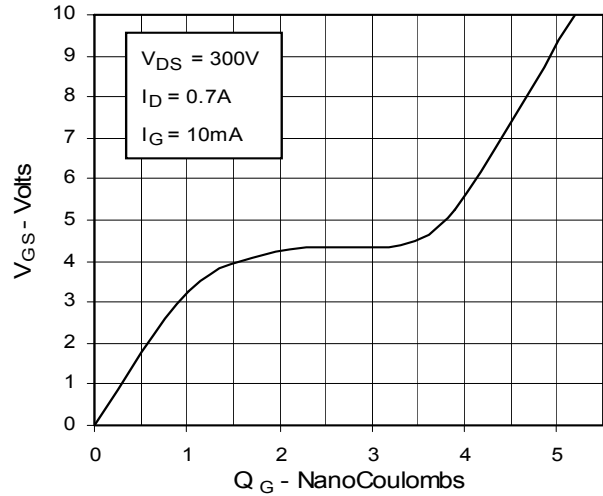


Fig. 11. Capacitance

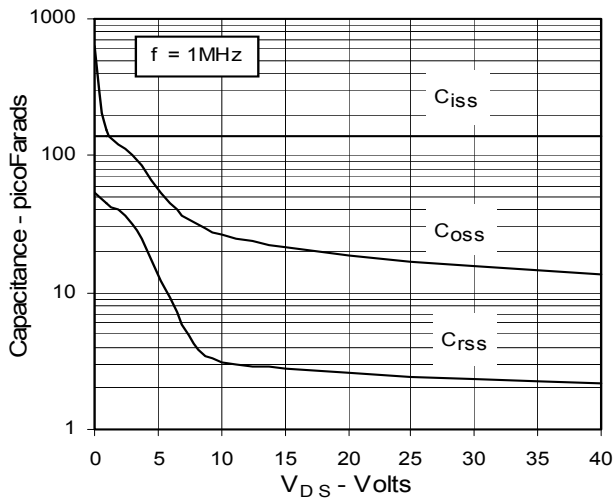
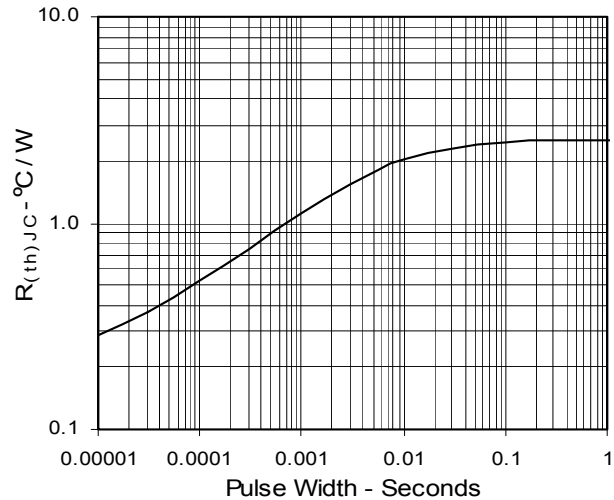


Fig. 12. Maximum Transient Thermal Resistance



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